

What is claimed is:

1. A copper foil for use in laser beam drilling, comprising a particle layer 0.01 to 3 μm thick which is formed at least on a surface thereof which the laser beam enters by plating
5 said surface with at least one or more kinds of metals comprising copper.
2. The copper foil for use in laser beam drilling according to claim 1, further comprising an over-plated coating which is formed on the surface of said particle layer formed by
10 said metal plating without changing the surface configuration.